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- (71) **Applicant:** **APPLIED MATERIALS, INC.** [US/US];
3050 Bowers Avenue, Santa Clara, California 95054 (US).
- (72) **Inventors:** **CHONG, Yau Loong**; c/o Applied Materials
South East Asia Pte. Ltd., 8 Upper Changi Road North,
Singapore 506906 (SG). **VOLETI, Venkatakaushik**; c/o
Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers
Avenue, Santa Clara, California 95054 (US). **WANG,
Ruiping**; c/o Applied Materials, Inc., Law Dept., M/S
1269, 3050 Bowers Avenue, Santa Clara, California 95054
(US). **VAEZ-IRAVANI, Mehdi**; c/o Applied Materials,
Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa
Clara, California 95054 (US).

- (74) **Agent:** **STEVENS, Joseph J.** et al.; PATTERSON +
SHERIDAN LLP, 24 GREENWAY PLAZA, SUITE 1600,
HOUSTON, Texas 77046 (US).

- (81) **Designated States** (*unless otherwise indicated, for every
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DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
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- (54) **Title:** USE OF ALTERNATING LAYER PATTERNS APPROACH FOR EFFECTIVE OVERLAY METROLOGY IN MULTI-STACK DIE APPLICATIONS

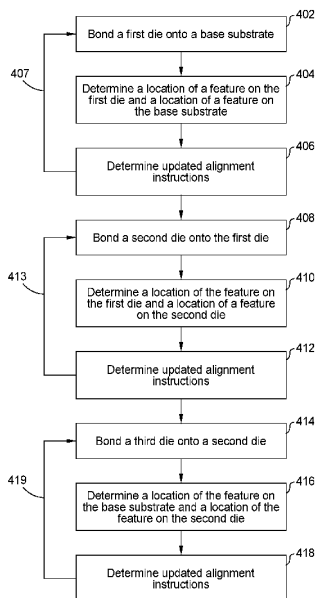


FIG. 4

- (57) **Abstract:** Embodiments of the disclosure include a method for forming a device comprising generating an image of a second die that is bonded on a first die that is bonded on a base substrate, the first die having a first feature formed on a first surface of the first die and the second die having a second feature formed on a second surface of the second die, determining a relative displacement between portions of the first feature and the second feature based on the generated image, and determining updated alignment instructions based on the determined relative displacement.

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